



Material Content Data Sheet



Sales Product Name		BGM 15MA12 E6327		Issued		20. July 2018		
MA#		MA001333288						
Package		PG-ATSLP-12-2		Weight*		3.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.186	5.10	5.10	51019	51019
bumps	non noble metal	copper	7440-50-8	0.022	0.59	0.59	5910	5910
encapsulation	organic material	carbon black	1333-86-4	0.013	0.35		3522	
	plastics	epoxy resin	-	0.373	10.21		102135	
	inorganic material	silicondioxide	60676-86-0	2.184	59.89	70.45	598722	704379
leadfinish	noble metal	gold	7440-57-5	0.024	0.67		6662	
	non noble metal	nickel	7440-02-0	0.028	0.76	1.43	7598	14260
substrate	organic material	carbon black	1333-86-4	0.001	0.02		250	
	plastics	epoxy resin	-	0.036	0.97		9748	
	inorganic material	silicondioxide	60676-86-0	0.267	7.33		73317	
	non noble metal	copper	7440-50-8	0.444	12.18	20.50	121786	205101
ubm	non noble metal	copper	7440-50-8	0.000	0.01	0.01	90	138
	non noble metal	titanium	7440-32-6	0.000	0.00		32	
	non noble metal	tungsten	7440-33-7	0.000	0.00		16	
solder	noble metal	silver	7440-22-4	0.000	0.01		75	
	non noble metal	tin	7440-31-5	0.012	0.32	0.33	3176	3251
solder resists	inorganic material	bariumsulfate	7727-43-7	0.013	0.34		3427	
	inorganic material	silicondioxide	60676-86-0	0.012	0.34		3388	
	plastics	acrylic resin	-	0.033	0.91	1.59	9127	15942
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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